HARRIS SEMICONDUCTOR

CD74FCT163244

December 1996

Fast CMOS 3.3V 16-Bit Buffer/Line Driver

Features

- **Advanced 0.6 micron CMOS Technology**
- **Advanced Low Power CMOS Operation**
- **Can Serve as a 5V to 3V Translator**
- **Excellent Output Drive Capability:**
  - **Balanced Drives (24mA Sink and Source)**
  - **Compatible with LVC™ Class of Products**
- **Pin Compatible with Industry Standard Double-Density Pinouts**
- **Low Ground Bounce Outputs**
- **Hysteresis on All Inputs**
- **Inputs Can Be Driven by 3.3V or 5V Devices**
- **Multiple Center Pin and Distributed V_{CC}/GND Pins Minimizing Switching Noise**

Ordering Information

PART NUMBER	TEMP. RANGE (^oC)	PACKAGE	PKG. NO.
CD74FCT163244AMT	-40 to 85	48 Ld TSSOP	M48.240-P
CD74FCT163244ASM	-40 to 85	48 Ld SSOP	M48.300-P
CD74FCT163244CMT	-40 to 85	48 Ld TSSOP	M48.240-P
CD74FCT163244CSM	-40 to 85	48 Ld SSOP	M48.300-P
CD74FCT163244MT	-40 to 85	48 Ld TSSOP	M48.240-P
CD74FCT163244SM	-40 to 85	48 Ld SSOP	M48.300-P

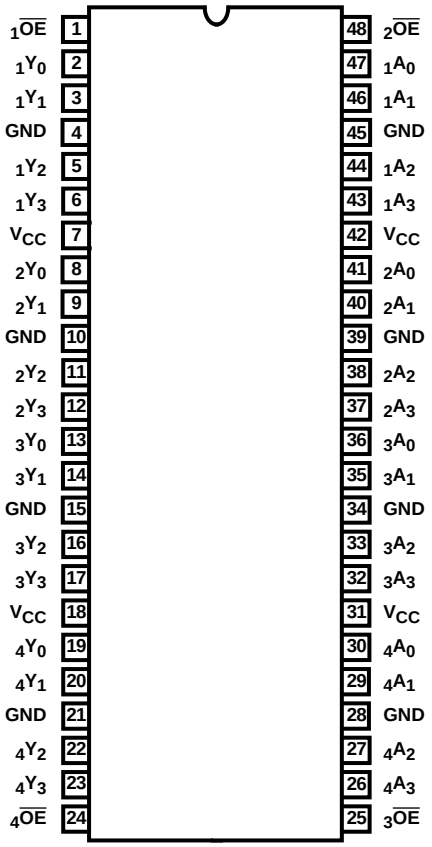
NOTE: When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.

Description

The CD74FCT163244 is a 16-bit buffer/line driver designed for applications driving high capacitive loads and low impedance backplanes. This high-speed, low power device offers bus/backplane interface capability and a flow-through organization for ease of board layout. This device is designed with three-state controls to operate in a Quad-Nibble, Dual-Byte, or a single 16-bit word mode.

Pinout

CD74FCT163244
(SSOP, TSSOP)
TOP VIEW



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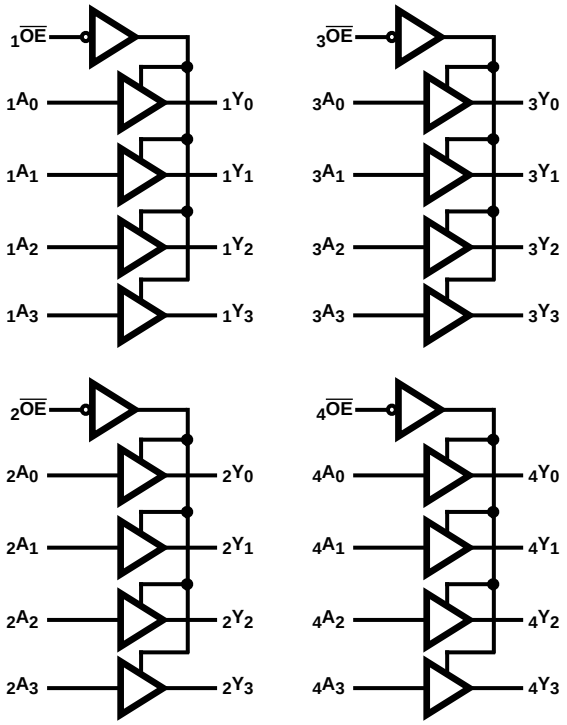
Functional Block Diagram



TRUTH TABLE (NOTE 1)

INPUTS		OUTPUTS
$_X\overline{OE}$	$_XA_X$	$_XY_X$
L	L	L
L	H	H
H	X	Z

NOTE:

1. H = High Voltage Level
   L = Low Voltage Level
   X = Don't Care
   Z = High Impedance

Pin Descriptions

PIN NAME	DESCRIPTION
$_X\overline{OE}$	Three-State Output Enable Inputs (Active LOW)
$_XA_X$	Inputs
$_XY_X$	Three-State Outputs
GND	Ground
V_{CC}	Power

Absolute Maximum Ratings

DC Input Voltage . . . . . -0.5V to 7.0V
DC Output Current 120mA

Operating Conditions

Operating Temperature Range . . . . . -40^oC to 85^oC
Supply Voltage to Ground Potential
Inputs and V_{CC} Only. . . . . -0.5V to 7.0V
Supply Voltage to Ground Potential
Outputs and D/O Only. . . . . -0.5V to 7.0V

Thermal Information

Thermal Resistance (Typical, Note 2)	θ_{JA} ($^oC/W$)
TSSOP Package	94
SSOP Package	76

Maximum Junction Temperature . . . . . 150^oC
Maximum Storage Temperature Range . . . . . -65^oC to 150^oC
Maximum Lead Temperature (Soldering 10s) . . . . . 300^oC
(Lead Tips Only)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTES:

2. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

Electrical Specifications

PARAMETERS	SYMBOL	(NOTE 3) TEST CONDITIONS		MIN	(NOTE 4) TYP	MAX	UNITS
DC ELECTRICAL SPECIFICATIONS Over the Operating Range, $T_A = -40^oC$ to 85^oC, $V_{CC} = 2.7V$ to $3.6V$							
Input HIGH Voltage (Input Pins)	V_{IH}	Guaranteed Logic HIGH Level		2.2	-	5.5	V
Input HIGH Voltage (I/O Pins)	V_{IH}	Guaranteed Logic HIGH Level		2.0	-	V_{CC} + 0.5	V
Input LOW Voltage (Input and I/O Pins)	V_{IL}	Guaranteed Logic LOW Level		-0.5	-	0.8	V
Input HIGH Current (Input Pins)	I_{IH}	V_{CC} = Max	V_{IN} = 5.5V	-	-	±1	µA
Input HIGH Current (I/O Pins)	I_{IH}	V_{CC} = Max	$V_{IN} = V_{CC}$	-	-	±1	µA
Input LOW Current (Input Pins)	I_{IL}	V_{CC} = Max	V_{IN} = GND	-	-	±1	µA
Input LOW Current (I/O Pins)	I_{IL}	V_{CC} = Max	V_{IN} = GND	-	-	±1	µA
High Impedance Output Current (Three-State)	I_{OZH}	V_{CC} = Max	$V_{OUT} = V_{CC}$	-	-	±1	µA
	I_{OZL}	V_{CC} = Max	V_{OUT} = GND	-	-	±1	µA
Clamp Diode Voltage	V_{IK}	V_{CC} = Min, I_{IN} = -18mA		-	-0.7	-1.2	V
Output HIGH Current	I_{ODH}	$V_{CC} = 3.3V$, $V_{IN} = V_{IH}$ or V_{IL}, $V_O = 1.5V$ (Note 5)		-36	-60	-110	mA
Output LOW Current	I_{ODL}	$V_{CC} = 3.3V$, $V_{IN} = V_{IH}$ or V_{IL}, $V_O = 1.5V$ (Note 5)		50	90	200	mA
Output HIGH Voltage	V_{OH}	V_{CC} = Min, $V_{IN} = V_{IH}$ or V_{IL}	I_{OH} = -0.1mA	V_{CC} - 0.2	-	-	V
			I_{OH} = -3mA	2.4	3.0	-	V
		$V_{CC} = 3.0V$, $V_{IN} = V_{IH}$ or V_{IL}	I_{OH} = -8mA	2.4 (Note 8)	3.0	-	V
			I_{OH} = -24mA	2.0	-	-	V
Output LOW Voltage	V_{OL}	V_{CC} = Min, $V_{IN} = V_{IH}$ or V_{IL}	I_{OL} = 0.1mA	-	-	0.2	V
			I_{OL} = 16mA	-	0.2	0.4	V
			I_{OL} = 24mA	-	0.3	0.5	V

Electrical Specifications (Continued)

PARAMETERS	SYMBOL	(NOTE 3) TEST CONDITIONS		MIN	(NOTE 4) TYP	MAX	UNITS
Short Circuit Current (Note 6)	I_{OS}	V_{CC} = Max (Note 5), V_{OUT} = GND		-60	-85	-240	mA
Input Hysteresis	V_H			-	150	-	mV
CAPACITANCE $T_A = 25^oC$, f = 1MHz							
Input Capacitance (Note 7)	C_{IN}	V_{IN} = 0V		-	4.5	6	pF
Output Capacitance (Note 7)	C_{OUT}	V_{OUT} = 0V		-	5.5	8	pF
POWER SUPPLY SPECIFICATIONS							
Quiescent Power Supply Current	I_{CC}	V_{CC} = Max	V_{IN} = GND or V_{CC}	-	0.1	10	µA
Quiescent Power Supply Current TTL Inputs HIGH	ΔI_{CC}	V_{CC} = Max	V_{IN} = VCC - 0.6V (Note 9)	-	2.0	30	µA
Dynamic Power Supply Current (Note 10)	I_{CCD}	V_{CC} = Max, Outputs Open $_X\overline{OE}$ = GND One Bit Toggling 50% Duty Cycle	V_{IN} = V_{CC} V_{IN} = GND	-	50	75	µA/ MHz
Total Power Supply Current (Note 12)	I_C	V_{CC} = Max, Outputs Open f_I = 10MHz, 50% Duty Cycle $_X\overline{OE}$ = GND One Bit Toggling	V_{IN} = V_{CC} - 0.6V V_{IN} = GND	-	0.5	0.8	mA
		V_{CC} = Max, Outputs Open f_I = 2.5MHz, 50% Duty Cycle $_X\overline{OE}$ = GND 16 Bits Toggling	V_{IN} = V_{CC} - 0.6V V_{IN} = GND	-	2.0	3.3 (Note 11)	mA

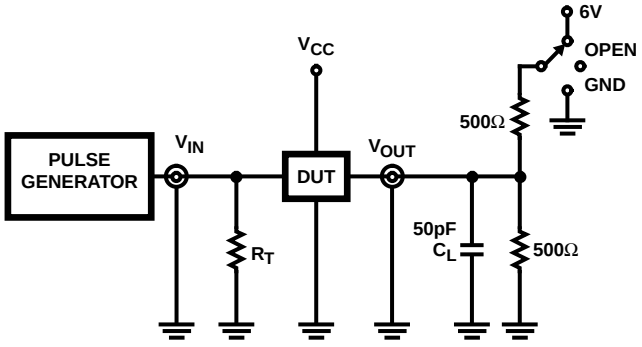
Switching Specifications Over Operating Range (Note 13)

PARAMETER	SYMBOL	(NOTE 14) TEST CONDITIONS	CD74FCT163244		CD74FCT163244A		CD74FCT163244C		UNITS
			(NOTE 15) MIN	MAX	(NOTE 15) MIN	MAX	(NOTE 15) MIN	MAX	
CD74FCT16244, CD74FCT162244									
Propagation Delay $_XA_X$ to $_XY_X$	t_{PLH}, t_{PHL}	C_L = 50pF, R_L = 500Ω	1.5	6.5	1.5	4.8	1.5	4.1	ns
Output Enable Time $_X\overline{OE}$ to $_XY_X$	t_{PZH}, t_{PZL}		1.5	8.0	1.5	6.2	1.5	5.8	ns
Output Disable Time (Note 16) $_X\overline{OE}$ to $_XY_X$	t_{PHZ}, t_{PLZ}		1.5	7.0	1.5	5.6	1.5	5.2	ns
Output Skew (Note 17)	$t_{SK(O)}$		-	0.5	-	0.5	-	0.5	ns

NOTES:

3. For conditions shown as Max or Min, use appropriate value specified under Electrical Characteristics for the applicable device type.
4. Typical values are at V_{CC} = 3.3V, 25^{o}C ambient and maximum loading.
5. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.
6. This parameter is guaranteed but not tested.
7. This parameter is determined by device characterization but is not production tested.
8. $V_{OH} = V_{CC} - 0.6V$ at rated current.
9. Per TTL driven input; all other inputs at V_{CC} or GND.
10. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
11. Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.
12. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
    $I_C = I_{CC} + \Delta I_{CC} D_H N_T + I_{CCD} (f_{CP}/2 + f_I N_I)$
    I_{CC} = Quiescent Current
    ΔI_{CC} = Power Supply Current for a TTL High Input
    D_H = Duty Cycle for TTL Inputs High
    N_T = Number of TTL Inputs at D_H
    I_{CCD} = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)
    f_{CP} = Clock Frequency for Register Devices (Zero for Non-Register Devices)
    N_{CP} = Number of Clock Inputs at f_{CP}
    f_I = Input Frequency
    N_I = Number of Inputs at f_I
    All currents are in milliamps and all frequencies are in megahertz.
13. Propagation Delays and Enable/Disable times are with V_{CC} = 3.3V ±0.3V, normal range. For V_{CC} = 2.7V, extended range, all Propagation Delays and Enable/Disable times should be degraded by 20%.
14. See test circuit and wave forms.
15. Minimum limits are guaranteed but not tested on Propagation Delays.
16. This parameter is guaranteed but not production tested.
17. Skew between any two outputs, of the same package, switching in the same direction. This parameter is guaranteed by design.

Test Circuits and Waveforms



SWITCH POSITION

TEST	SWITCH
t_{PLZ}, t_{PZL}, Open Drain	6V
t_{PHZ}, t_{PZH}	GND
t_{PLH}, t_{PHL}	Open

DEFINITIONS:

C_L = Load capacitance, includes jig and probe capacitance.

R_T = Termination resistance, should be equal to Z_{OUT} of the Pulse Generator.

NOTE:

18. Pulse Generator for All Pulses: Rate ≤ 1.0MHz; Z_{OUT} ≤ 50Ω; t_f, t_r ≤ 2.5ns.

FIGURE 1. TEST CIRCUIT

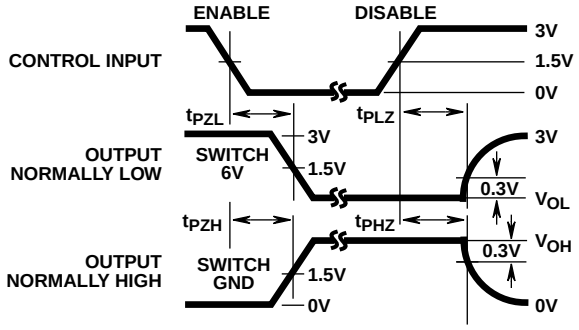


FIGURE 2. ENABLE AND DISABLE TIMING

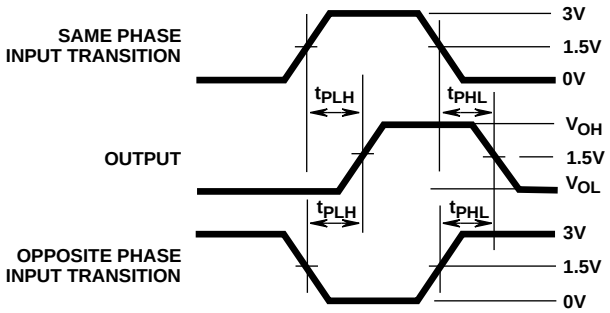
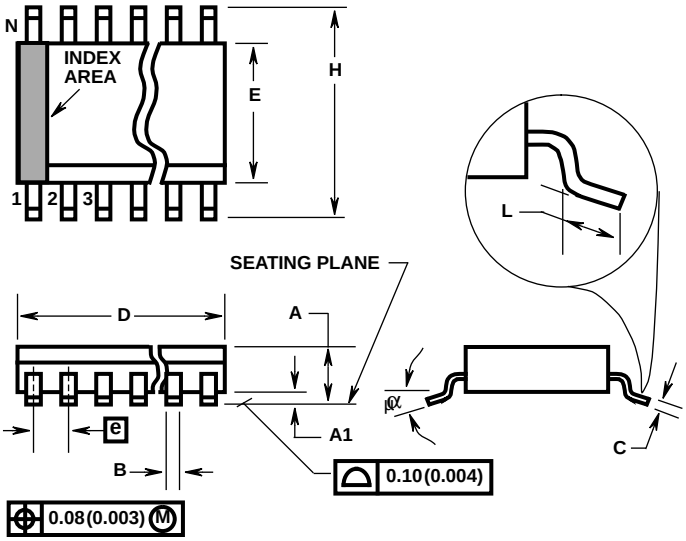


FIGURE 3. PROPAGATION DELAY

Thin Shrink Small Outline Plastic Packages (TSSOP)



M48.240-P

48 LEAD THIN SHRINK SMALL OUTLINE PLASTIC PACKAGE

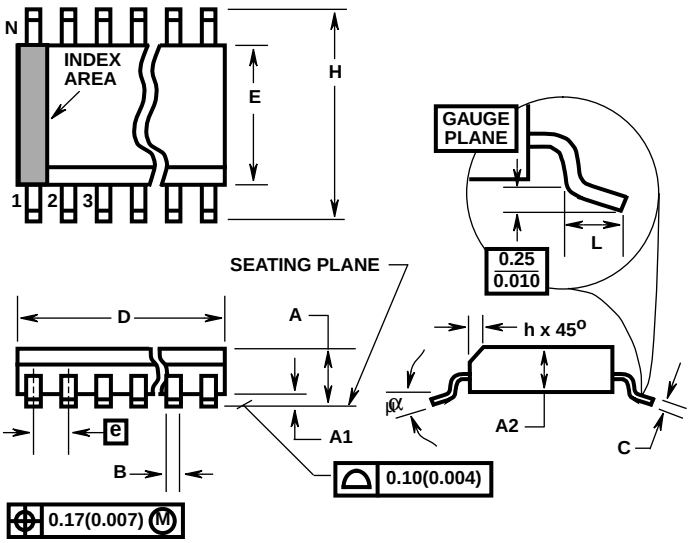
SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.041	0.047	1.05	1.20	-
A1	0.002	0.006	0.05	0.15	-
B	0.007	0.010	0.178	0.254	-
C	0.004	0.008	0.102	0.203	-
D	0.488	0.496	12.40	12.59	1
E	0.236	0.244	6.00	6.19	2
e	0.0197 BSC		0.50 BSC		-
H	0.307	0.330	7.80	8.38	-
L	0.020	0.030	0.51	0.76	3
N	48		48		4
α	0^o	8^o	0^o	8^o	-

Rev. 0 6/96

NOTES:

1. Dimension “D” does not include mold flash, protrusions or gate burrs.
2. Dimension “E” does not include interlead flash or protrusions.
3. “L” is the length of terminal for soldering to a substrate.
4. “N” is the number of terminal positions.
5. Terminal numbers are shown for reference only.
6. Controlling dimension: INCHES. Converted millimeter dimensions are not necessarily exact.

Shrink Small Outline Plastic Packages (SSOP)



M48.300-P

48 LEAD SHRINK SMALL OUTLINE PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.096	0.108	2.44	2.74	-
A1	0.008	0.016	0.20	0.41	-
A2	0.088	0.092	2.24	2.34	-
B	0.008	0.0135	0.20	0.34	-
C	0.005	0.010	0.13	0.25	-
D	0.620	0.630	15.75	16.00	2
E	0.291	0.299	7.39	7.59	3
e	0.025 BSC		0.635 BSC		-
H	0.395	0.415	10.03	10.54	-
h	0.015	0.025	0.381	0.635	-
L	0.020	0.040	0.51	1.01	4
N	48		48		5
α	0^o	8^o	0^o	8^o	-

Rev. 0 5/96

NOTES:

1. These package dimensions are within allowable dimensions of JECEC MO-118-AA, Issue B.
2. Dimension “D” does not include mold flash, protrusions or gate burrs.
3. Dimension “E” does not include interlead flash or protrusions.
4. “L” is the length of terminal for soldering to a substrate.
5. “N” is the number of terminal positions.
6. Terminal numbers are shown for reference only.
7. Controlling dimension: INCHES. Converted millimeter dimensions are not necessarily exact.

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